AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that radiates light from a light emission surface provided on a [[side]] <u>substrate</u> opposite to an electrode forming surface of said light emitting element;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is <u>mounted on the substrate and</u> optically connected with the light emission surface and has a light distribution characteristic based on its three-dimensional shape, said transparent structure being mounted on a substrate positioned on a side opposite said light emitting element; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure.

- (Original) The light emitting apparatus according to claim 1, wherein:
 the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.
- 3. (Original) The light emitting apparatus according to claim 1, wherein: the transparent structure has a thickness of half that of the semiconductor light emitting element to twice the length of a shorter side of the semiconductor light emitting element.

- 4. (Original) The light emitting apparatus according to claim 1, wherein:
 the transparent structure has a microscopic uneven surface to diffuse light.
- (Original) The light emitting apparatus according to claim 1, wherein:
 the transparent structure has a reflection layer formed on its surface.
- 6. (Original) The light emitting apparatus according to claim 1, wherein: one of the lead frames has a cup portion, and the transparent structure is fixed on the cup portion through adhesive resin with light diffusion material mixed therein.
- 7. (Original) The light emitting apparatus according to claim 1, wherein: the electrodes do not transmit light.
- (Currently Amended) A light emitting apparatus, comprising:
 a semiconductor light emitting element that radiates light from a light emission
 surface provided on a substrate opposite an electrode forming surface;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is <u>mounted on the substrate and</u> optically connected with the light emission surface and has a light distribution characteristic based on its threedimensional shape; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure, the light transmitting resin including a phosphor to wavelength-convert light emitted from the semiconductor light emitting element.

- (Original) The light emitting apparatus according to claim 8, wherein:
 the light transmitting resin contains two or more kinds of phosphors.
- 10. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises the substrate, a buffer layer, an n-type semiconductor layer, a light-emitting layer, and a p-type semiconductor layer.
- 11. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises a gallium nitride system compound semiconductor.
- 12. (Previously Presented) The light emitting apparatus according to claim 1, wherein the transparent structure comprises a light transmitting material comprising at least one of SiO₂, Al₂O₃, SiC, Si₃N₄, AlN, ZrO₂, borosilicate glass, and alumino-silicate glass.
- 13. (Previously Presented) The light emitting apparatus according to claim 1, wherein the substrate comprises sapphire.

- 14. (Currently Amended) The light emitting apparatus according to claim 1, wherein the transparent structure is connected to the light emission surface mounted on the substrate by an adhesive layer.
- 15. (Previously Presented) The light emitting apparatus according to claim 14, wherein the adhesive layer comprises a transparent adhesive.
- 16. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that radiates light from a light emission surface provided on [[an]] a substrate opposite [[side]] to an electrode forming surface of said light emitting element;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is <u>mounted on the substrate and</u> optically connected with the light emission surface and has a light distribution characteristic based on its threedimensional shape; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure,

wherein the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.